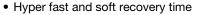


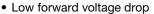
Hyperfast Rectifier, 30 A FRED Pt®



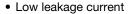
PRIMARY CHARACTERISTICS					
I _{F(AV)}	30 A				
V_{R}	650 V				
V _F at I _F at 125 °C	1.6 V				
t _{rr}	27 ns				
T _J max.	175 °C				
Package	TO-220AC 2L				
Circuit configuration	Single				

FEATURES









True 2 pin package

AEC-Q101 qualified

 Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



RoHS

HALOGEN FREE

DESCRIPTION / APPLICATIONS

Ultra low V_F , soft-switching hyper fast rectifiers optimized for discontinuous (critical) mode (DCM) power factor correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Repetitive peak reverse voltage	V_{RRM}		650	V
Average rectified forward current	I _{F(AV)}	T _C = 120 °C	30	۸
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	210	A
Operating junction and storage temperature	T _J , T _{Stg}		-55 to +175	°C

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL TEST CONDITIONS MIN. TYP. MA				MAX.	UNITS		
Breakdown voltage, blocking voltage	V_{BR}, V_{R}	I _R = 250 μA	650	-				
Forward voltage	V _F	I _F = 30 A	-	2.1	2.5 V			
		I _F = 30 A, T _J = 125 °C	-	1.6	1.7			
Devenue legicare guinnent	I _R	$V_R = V_R$ rated	-	0.02	30			
Reverse leakage current		T _J = 150 °C, V _R = V _R rated	-	50	300	00 μA		
Junction capacitance	C _T	V _R = 200 V	-	22	-	pF		
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH		



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	TEST CONDITIONS			MAX.	UNITS	
Reverse recovery time t _{rr}	trr	T _J = 25 °C	$I_F = 1 \text{ A}$ $dI_F/dt = 100 \text{ A/}\mu\text{s}$ $V_R = 30 \text{ V}$	-	35	ı	ns	
	"	T _J = 25 °C	$I_F = 30 \text{ A}$ $dI_F/dt = 1000 \text{ A/}\mu\text{s}$ $V_R = 400 \text{ V}$	-	27	-		
		T _J = 125 °C		-	88	-		
Peak recovery current		T _J = 25 °C		-	15	-	Α	
reak recovery current	I _{RRM}	T _J = 125 °C		-	24	-	^	
Daviera and a series also and	0	T _J = 25 °C	N - 100 V	-	330	-	200	
Reverse recovery charge	Q _{rr}	T _J = 125 °C		-	1350	-	nC	

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Thermal resistance, junction to case	R_{thJC}		-	1.0	1.3			
Thermal resistance, junction to ambient	R_{thJA}	Typical socket mount	-	-	70	°C/W		
Thermal resistance, case to heat sink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	-	0.5			
Weight			-	0.2	-	g		
Weight			-	0.07	-	oz.		
Mounting torque			6.0	_	12	kgf · cm		
Wourting torque			(5.0)	_	(10)	(lbf · in)		
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C		
Marking device		Case style: TO-220AC 2L	ETX3007TH					

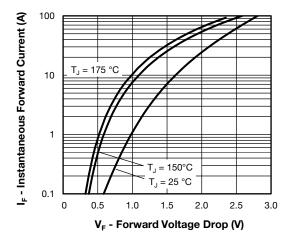


Fig. 1 - Typical Forward Voltage Drop Characteristics

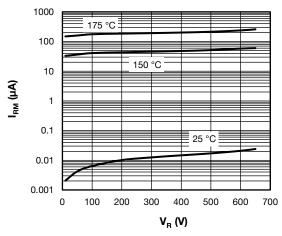


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

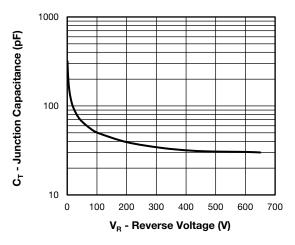


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

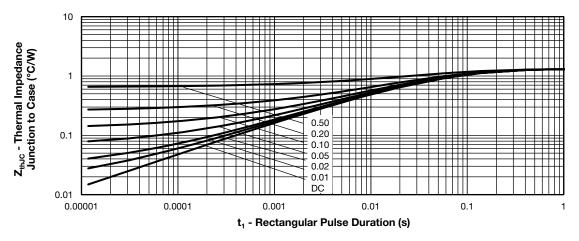


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

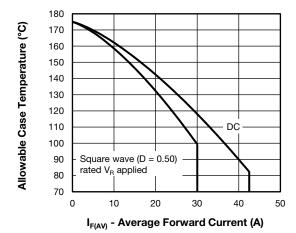


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

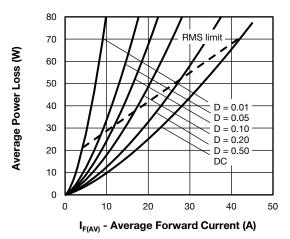


Fig. 6 - Forward Power Loss Characteristics

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Vishay Semiconductors

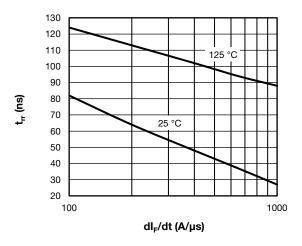


Fig. 7 - Typical Reverse Recovery Time vs. dI_{F}/dt

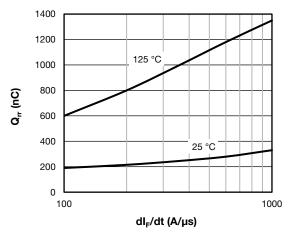
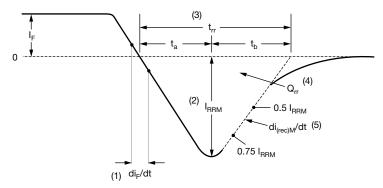


Fig. 8 - Typical Reverse Recovery Time vs. dl_E/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

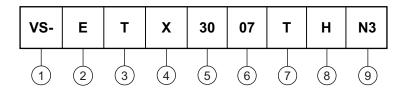
(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - E = single diode

3 - Package:

T = TO-220

4 - X = hyper fast recovery

5 - Current rating (30 = 30 A)

6 - Voltage rating (07 = 650 V)

7 - T = True 2 pin TO-220

8 - H = AEC-Q101 qualified

9 - Environmental digit:

N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

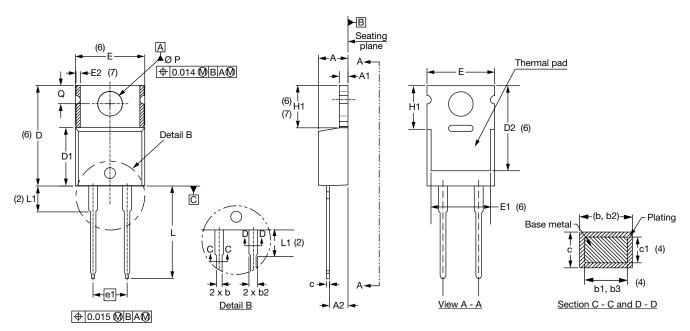
ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-ETX3007THN3	50	1000	Antistatic plastic tube			

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?96069			
Part marking information	www.vishay.com/doc?95391			
SPICE model	www.vishay.com/doc?96532			



TO-220AC 2L

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INC	HES	NOTES
STINIBUL	MIN.	MAX.	MIN.	MAX.	NOIES
Α	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.56	2.92	0.101	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
С	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.25	0.585	0.600	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	12.88	0.460	0.507	6
E	10.11	10.51	0.398	0.414	3, 6

SYMBOL	MILLIN	MILLIMETERS		INCHES		
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES	
E1	6.86	8.89	0.270	0.350	6	
E2	ı	0.76	-	0.030	7	
e1	4.88	5.28	0.192	0.208		
H1	5.84	6.86	0.230	0.270	6, 7	
L	13.52	14.02	0.532	0.552		
L1	3.32	3.82	0.131	0.150	2	
ØΡ	3.54	3.73	0.139	0.147		
Ø	2.60	3.00	0.102	0.118		

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- $^{(7)}$ Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC® TO-220, except D2, where JEDEC® minimum is 0.480"



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Vishay

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